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(54) Title: ZINC OXIDE DIODES FOR OPTICAL INTERCONNECTIONS

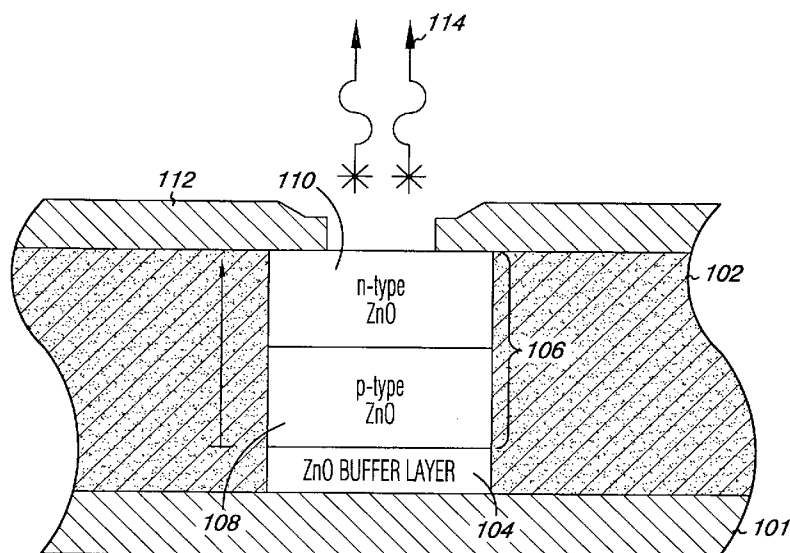


Fig. 1A

(57) Abstract: The present disclosure includes methods, devices, and systems for zinc oxide diodes for optical interconnections. One system includes a ZnO emitter confined within a circular geometry in an oxide layer on a silicon substrate. An optical waveguide is formed in the oxide layer and has an input coupled to the ZnO emitter. A detector is coupled to an output of the optical waveguide.

WO 2008/112075 A1